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The New Frontier Al for Manufacturing and Test

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Agenda

- 1. The Challenge
- 2. The Opportunity
- 3. <u>AI-Driven Solutions</u>
- 4. Conclusion

The Challenge

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3 challenges the semiconductor industry must tackle



innovations in 3D



operating through a complex global supply chain



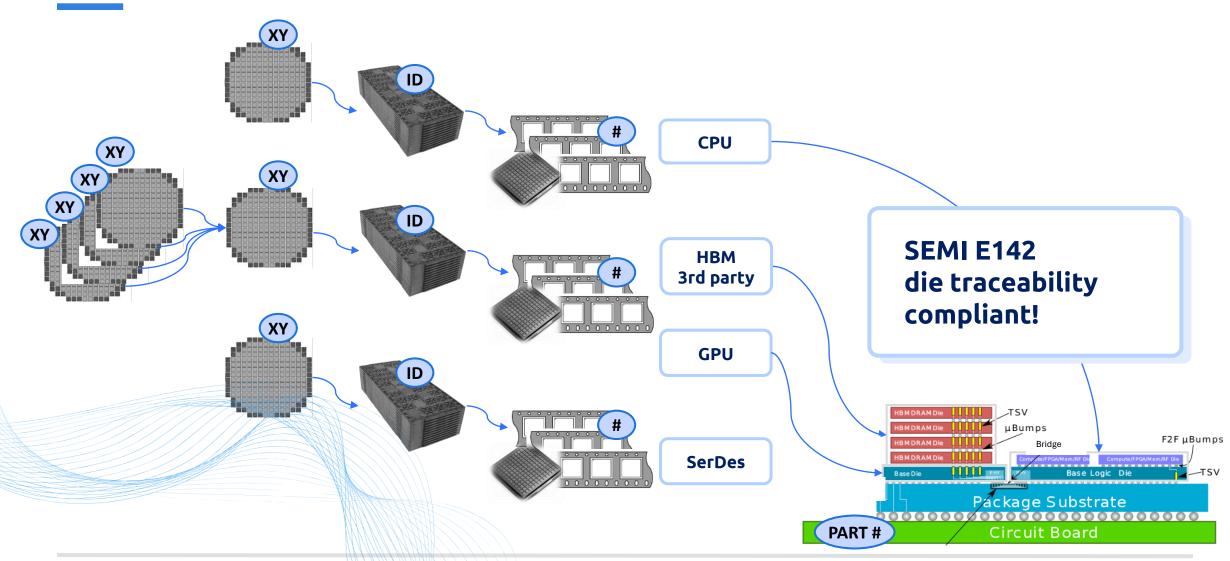
leveraging AI at all levels, from design to manufacturing



centers



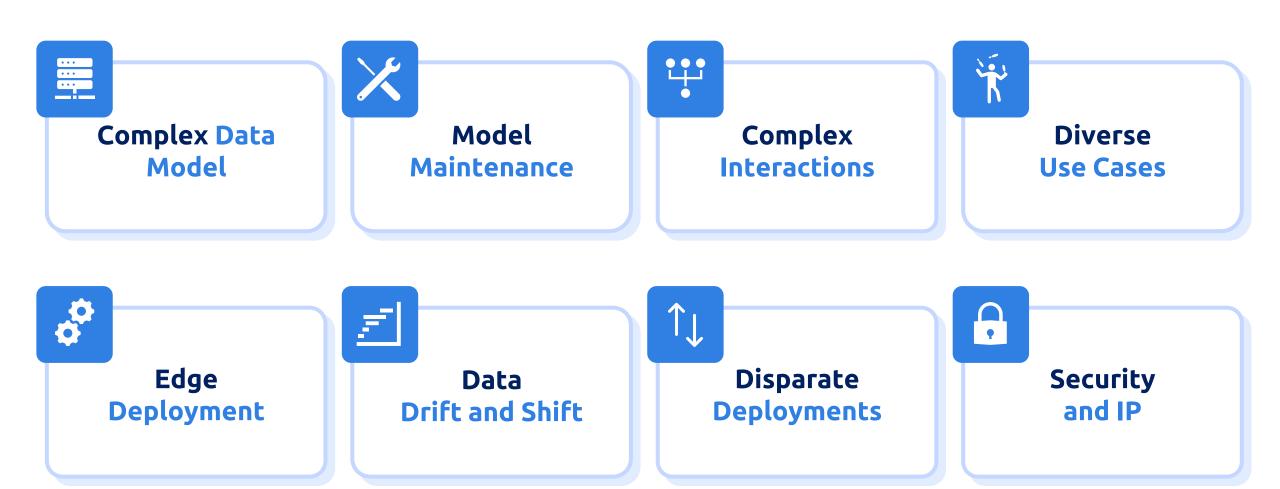
Data Complexity of Advanced Packaging



Testing Across A Globally Distributed Supply Chain



What Makes AI for Semiconductor Different and Difficult



PDF/SOLUTIONS**

the leading commercial data, analytics, and mission critical platform spanning the semiconductor and electronics industry

we provide solutions in three areas:



characterization & technology development



smart manufacturing & analytics



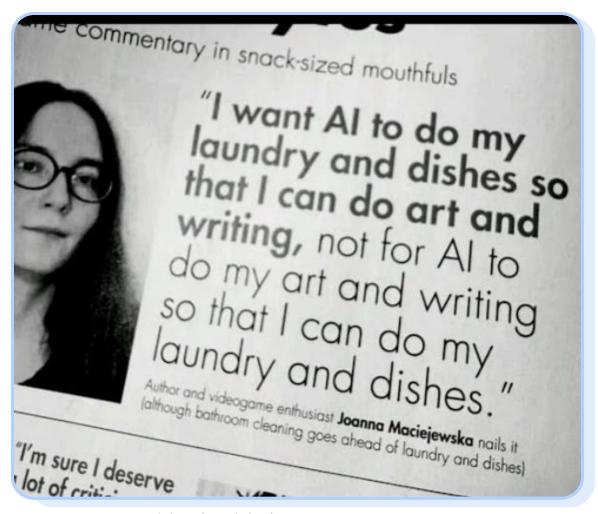
supply chain orchestration



The Opportunity

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Opportunity: Al for Test



data



infrastructure

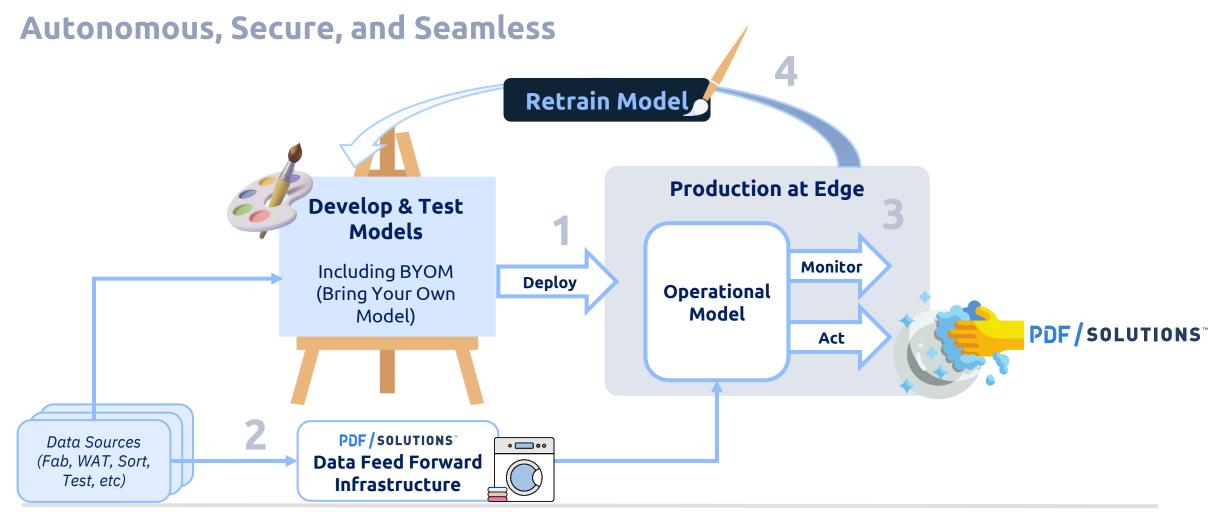


model

Source: Joanna Maciejewska, LinkedIn

Al Infrastructure:

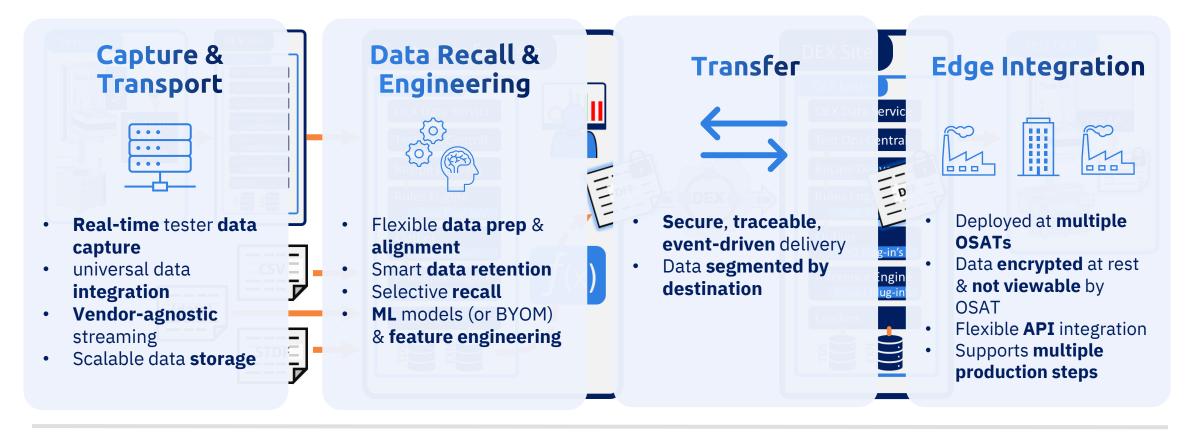
Create, Manage & Control Models Across Lifecycles



PDF/SOLUTIONS* Data Feed Forward Infrastructure

PDF Solutions Infrastructure for Data Feed Forward

enables sharing & access of test data across different stages of production delivering actionable insights upstream and downstream, allowing customers to optimize test operations, improve yield, and accelerate decision-making.



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Predictive Test

Spend test \$ on units that need them most. Predict which tests will pass

Inputs

- WAT & CP data, for features
- FT data, for labeling
- Test time pareto

Outputs

Die by die skip list, by tests

3



Target	Current Failure Rate (PPM)	DPPM (with ML)	ML Fail Captured%	ML Skip %
FT_Test_A	82	0.0	100.00%	99.26%
FT_Test_B	88	0.0	100.00%	98.49%
FT_Test_C	220	0.0	100.00%	96.63%
FT_Test_D	839	0.0	100.00%	95.98%
FT_Test_E	540	2.9	99.43%	95.25%
FT_Test_F	584	0.0	100.00%	94.64%
FT_Test_G	255	0.9	99.60%	88.14%

Predictive Test

Spend test \$ on units that need them most. Predict which tests will pass

Inputs

- WAT & CP data, for
- FT data, for labeling
- Test time pareto

Outputs

Die by die skip list, by tests

Predictive Burn-In

Eliminate costly burn-in Predict which tests will pass burn-in

Inputs

- WAT & CP data, for features • BI failure data,
- for labeling

Outputs

Modified die-by-die binning, "needs BI" or "skips BI"



Burn-In

Predictive Test

Spend test \$ on units that need them most. Predict which tests will pass

Inputs

- WAT & CP data, for features
- FT data, for labeling
- Test time pareto

Outputs

Die by die skip list, by tests

Predictive Binning

Find failures early. Predict which tests will fail

Inputs

- WAT & CP data, for
- FT data, for labeling

Outputs

Modified wafermap, to scrap units early

Predictive Burn-In

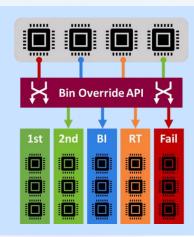
Eliminate costly burn-in Predict which tests will pass burn-in

Inputs

- WAT & CP data. for features • BI failure data.
- for labeling

Outputs

Modified die-by-die binning, "needs BI" or "skips BI"



Predictive Test

Spend test \$ on units that need them most. Predict which tests will pass

Inputs

- WAT & CP data, for features
- FT data, for labeling
- Test time pareto

Outputs

Die by die skip or add list, by tests

Predictive Binning

Find failures early. Predict which tests will fail

Inputs

- WAT & CP data, for features
- FT data, for labeling

Outputs

Modified wafermap, to scrap units early

Predictive Burn-In

Eliminate costly burn-in Predict which tests will pass burn-in

Inputs

- WAT & CP data. for features • BI failure data.
- for labeling

Outputs

Modified die-by-die binning, "needs BI" or "skips BI"

save time reduce cost improve quality

Conclusion

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Key Takeaways

AI-driven test is a continuum of data, model, and infrastructure



Semiconductorspecific data, over space and time



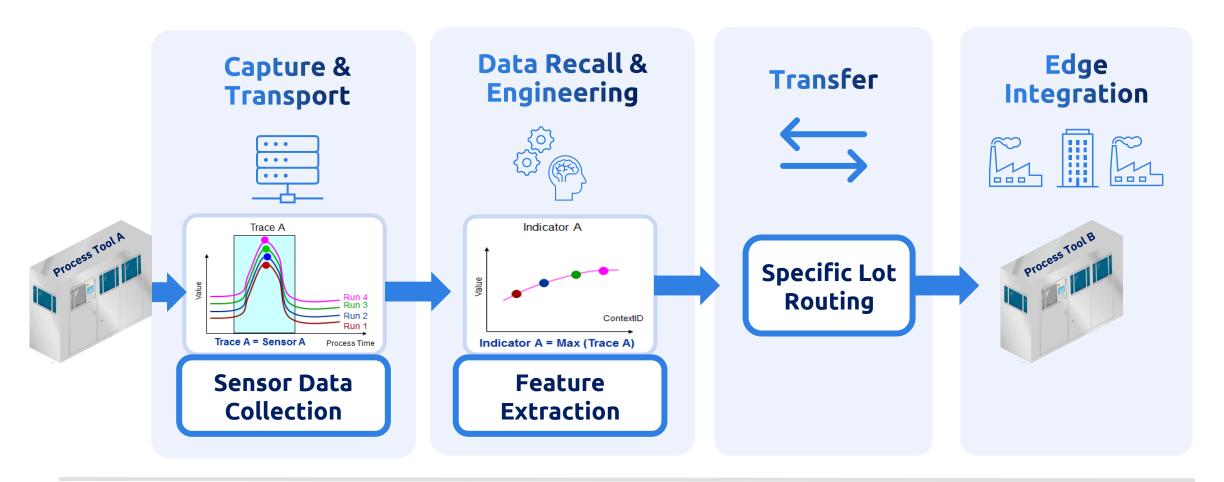
Connected view of a globally distributed supply chain



Al across the design, manufacturing, and test lifecycles

AI & Forwarding Data in Process Control

enable variability reduction using the same DFF infrastructure



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